

Metallizing a fluoropolymer substrate for forming conductor structures or a plasma etching mask on a circuit substrate

Publication number: DE19817388

Publication date: 1999-10-28

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Classification:






- international: C23C16/02; C23C16/06; C23C28/02; H05K3/14; H05K3/38; H05K1/03; C23C16/02; C23C16/06; C23C28/02; H05K3/14; H05K3/38; H05K1/03; (IPC1-7): H05K1/03; C23C16/18; C23C18/31; C23C28/02; H03K3/10

- european: C23C16/02D4; C23C16/06; C23C28/02B; H05K3/14C; H05K3/38E

Application number: DE19981017388 19980420

Priority number(s): DE19981017388 19980420

Also published as:

 WO9954525 (A3)
 WO9954525 (A2)
 EP1080247 (A3)
 EP1080247 (A2)
 US6706201 (B1)

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Abstract of DE19817388

A fluoropolymer substrate is metallized by arc discharge deposition of a nickel layer, prior to further metallization. A metallized substrate is produced by coating its fluoropolymer surface with a nickel layer by nickel compound decomposition in an arc discharge and then with a metal layer from a metallization bath. An Independent claim is also included for application of the above process to formation of conductor structures or a plasma etching mask on the fluoropolymer surfaces by selective etching or deposition of the metal layers using resists.

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